



Product Change Notification

Change Notification #: 115657 - 00
Change Title: TPM Module AXXTPMSP6,
PCN 115657-00, Product Design, Product
Material, Upgrade TPM Module Chip
Firmware
Date of Publication: July 07, 2017

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	July 22, 2017
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** Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® TPM Module AXXTPMSP6:

- Update the old TPM Module Chip with 5.50 Firmware version with the New TPM Chip with 5.61 Firmware version which is listed as certified TPM.

All new components are identical in form, fit, and function, to the current version.

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
AXXTPMSP6	958832	J59188-001	J59188-002

PCN Revision History:

Date of Revision: July 7, 2017	Revision Number: 00	Reason: Originally Published PCN
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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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